

Dual Enhancement Mode MOSFET (N-and P-Channel)

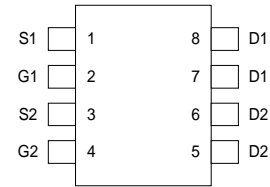
Features

- N-Channel
30V/6.9A, $R_{DS(ON)}=27.44m\Omega @V_{GS}=10V$
 $R_{DS(ON)}=41.16m\Omega @V_{GS}=4.5V$
- P-Channel
-30V/-6.9A, $R_{DS(ON)}=32.00m\Omega @V_{GS}=10.0V$
 $R_{DS(ON)}=50.00m\Omega @V_{GS}=4.5V$
- Super High Dense Cell Design for Extremely Low $R_{DS(ON)}$
- Reliable and Rugged
- SO-8 Package

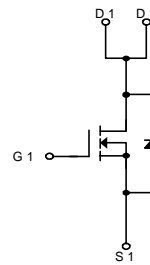
Applications

- Power Management in Notebook Computer , Portable Equipment and Battery Powered Systems.

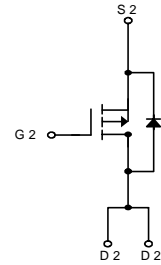
Pin Description



SO-8



N-Channel MOSFET



P-Channel MOSFET



Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		N-Channel	P-Channel	Unit
V_{DSS}	Drain-Source Voltage		30	-30	V
V_{GSS}	Gate-Source Voltage		± 20	± 20	
I_D^*	Maximum Drain Current – Continuous		6.9	-6.9	A
I_{DM}	Maximum Drain Current – Pulsed		28	-20	
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	2	2	W
T_J	Maximum Junction Temperature		150		$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-55 to 150		$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance – Junction to Ambient		62.5		$^\circ\text{C/W}$

* Surface Mounted on FR4 Board, $t \leq 10$ sec.

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Condition	4542			Unit	
			Min.	Typ.	Max.		
Static							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	N-Ch	30			V
			P-Ch	-30			
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=24V, V_{GS}=0V$	N-Ch			1	μA
		$V_{DS}=-24V, V_{GS}=0V$	P-Ch			-1	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	N-Ch	1	1.5	2	V
		$V_{DS}=V_{GS}, I_{DS}=-250\mu A$	P-Ch	-1	-1.5	-2	
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	N-Ch			± 100	nA
		$V_{GS}=\pm 20V, V_{DS}=0V$	P-Ch			± 100	
$R_{DS(ON)}^a$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=6.9A$	N-Ch			28	m Ω
		$V_{GS}=4.5V, I_{DS}=5A$				42	
		$V_{GS}=-10V, I_{DS}=-6.9A$	P-Ch			32	
		$V_{GS}=-4.5V, I_{DS}=-5A$				50	
V_{SD}^a	Diode Forward Voltage	$I_{SD}=2.0A, V_{GS}=0V$	N-Ch		0.7	1.0	V
		$I_{SD}=-2.0A, V_{GS}=0V$	P-Ch		-0.7	-1.0	

Notes

^a : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$



Electrical Characteristics (Cont.) ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Condition	4542			Unit
			Min.	Typ.	Max.	
Dynamic^b						
Q _g	Total Gate Charge	N-Channel V _{DS} =15V , I _{DS} = 6.9A	N-Ch	19	28	nC
			P-Ch	28	36	
Q _{gs}	Gate-Source Charge	V _{GS} =10V P-Channel	N-Ch	1.6		
			P-Ch	5		
Q _{gd}	Gate-Drain Charge	V _{DS} =-15V , I _{DS} =-6.9A V _{GS} =-10V	N-Ch	3.6		
			P-Ch	4		
t _{d(ON)}	Turn-on Delay Time	N-Channel V _{DD} =15V , I _{DS} =2A , V _{GEN} =10V , R _G =6Ω , R _L =7.5Ω	N-Ch	11	20	ns
			P-Ch	12	24	
T _r	Turn-on Rise Time	P-Channel V _{DD} =-15V , I _{DS} =-2A , V _{GEN} =-10V , R _G =6Ω , R _L =7.5Ω	N-Ch	17	28	
			P-Ch	15	29	
t _{d(OFF)}	Turn-off Delay Time	N-Channel V _{DD} =15V , I _{DS} =2A , V _{GEN} =10V , R _G =6Ω , R _L =7.5Ω	N-Ch	36	62	
			P-Ch	35	60	
T _f	Turn-off Fall Time	P-Channel V _{DD} =-15V , I _{DS} =-2A , V _{GEN} =-10V , R _G =6Ω , R _L =7.5Ω	N-Ch	20	36	
			P-Ch	15	30	
C _{iss}	Input Capacitance	N-Channel V _{GS} =0V, V _{DS} =25V	N-Ch	835		pF
			P-Ch	950		
C _{oss}	Output Capacitance	Frequency=1.0MHz P-Channel	N-Ch	145		
			P-Ch	160		
C _{rss}	Reverse Transfer Capacitance	V _{GS} =0V, V _{DS} =-25V Frequency=1.0MHz	N-Ch	15		
			P-Ch	110		

Notes

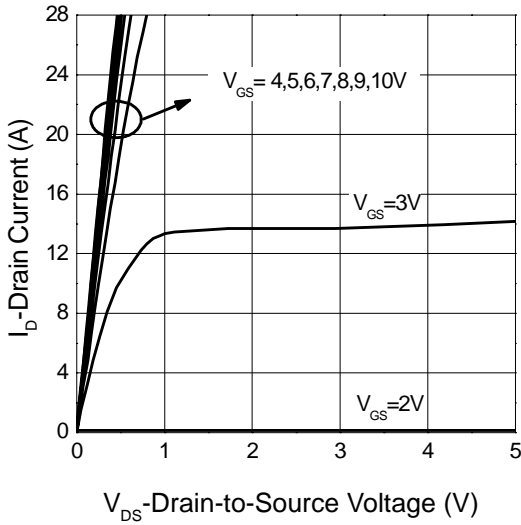
^b : Guaranteed by design, not subject to production testing



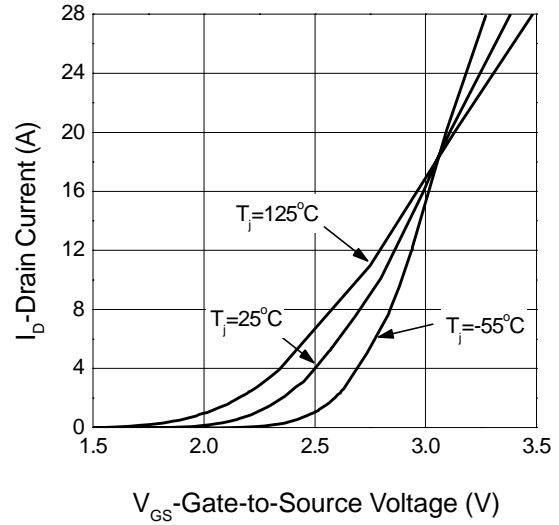
Typical Characteristics

N-Channel

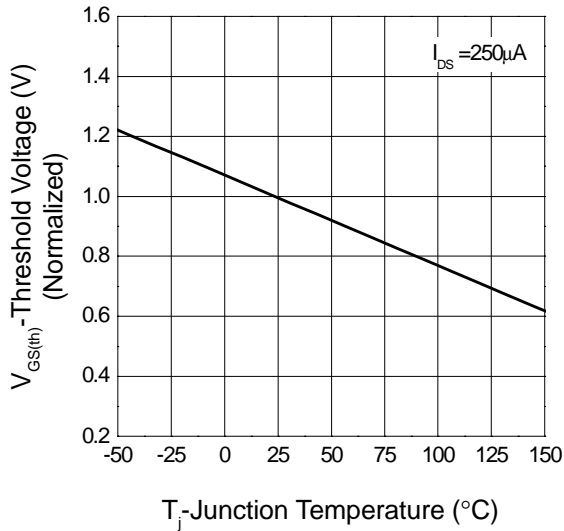
Output Characteristics



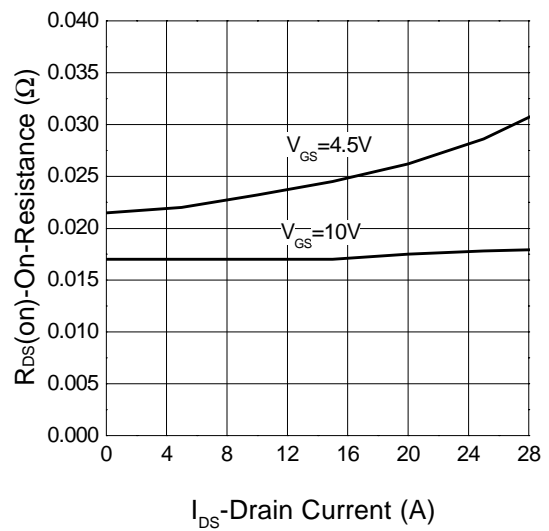
Transfer Characteristics



Threshold Voltage vs. Junction Temperature



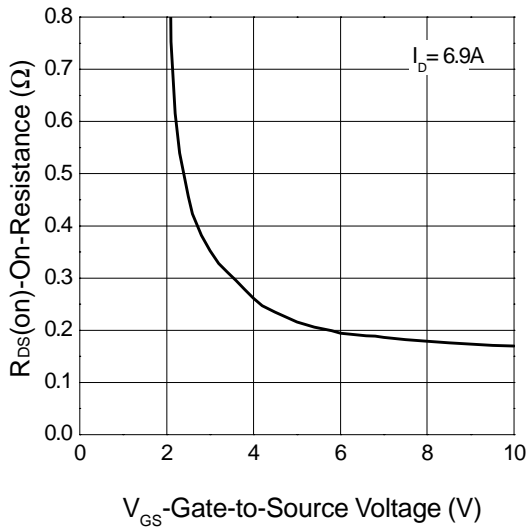
On-Resistance vs. Drain Current



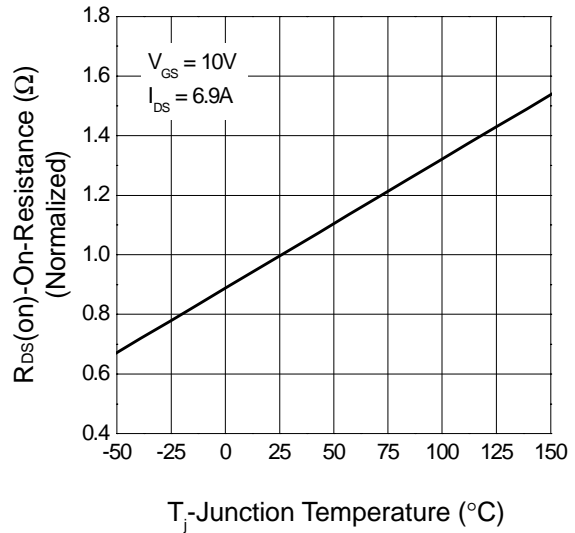
Typical Characteristics (Cont.)

N-Channel

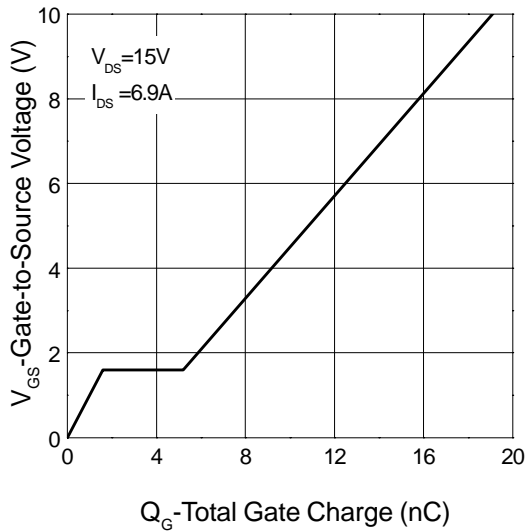
On-Resistance vs. Gate-to-Source Voltage



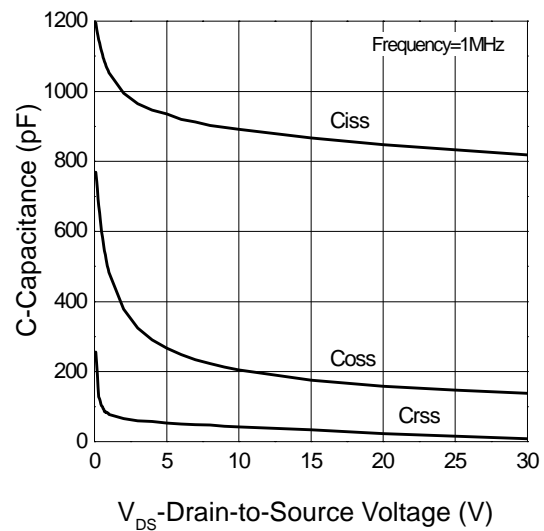
On-Resistance vs. Junction Temperature



Gate Charge

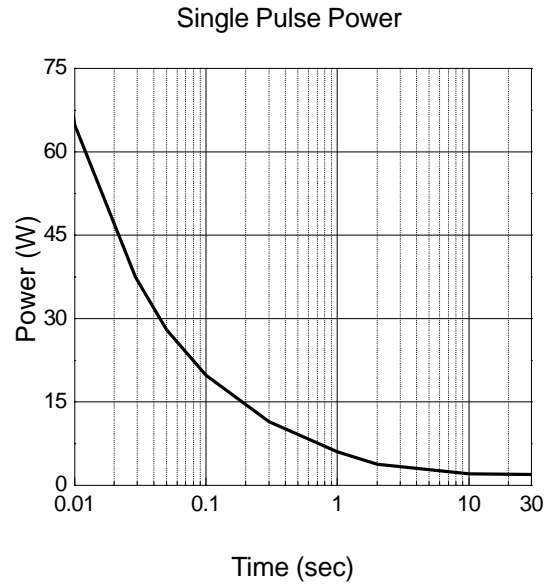
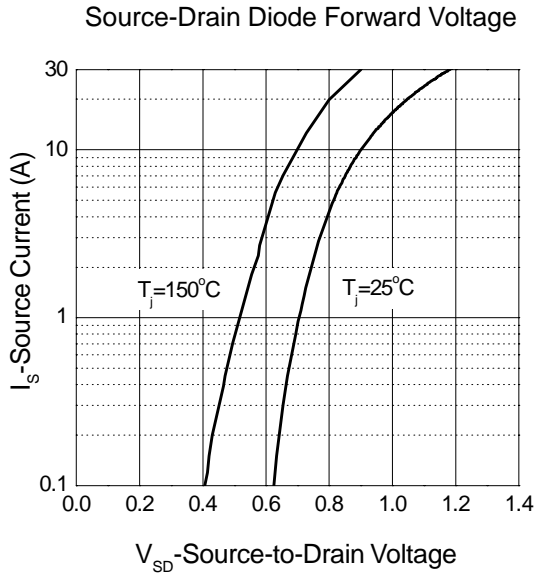


Capacitance Characteristics

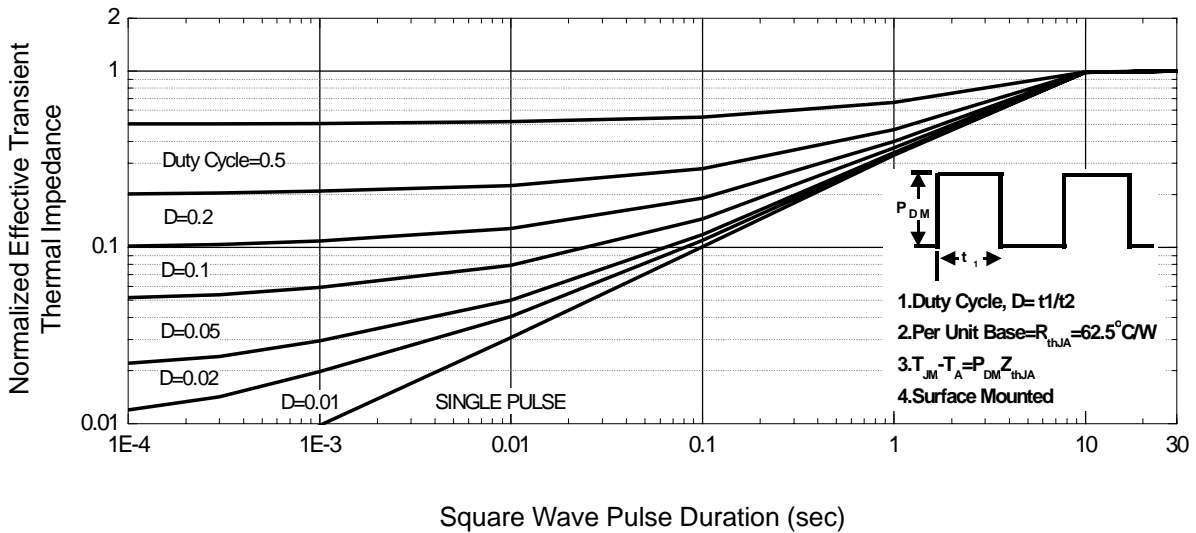


Typical Characteristics (Cont.)

N-Channel



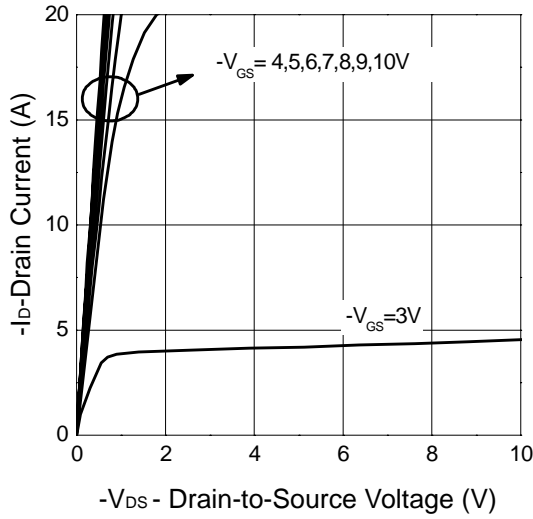
Normalized Transient Thermal Transient Impedance, Junction to Ambient



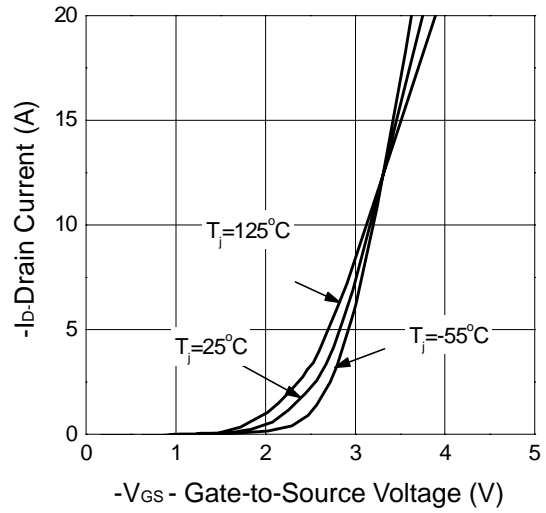
Typical Characteristics

P-Channel

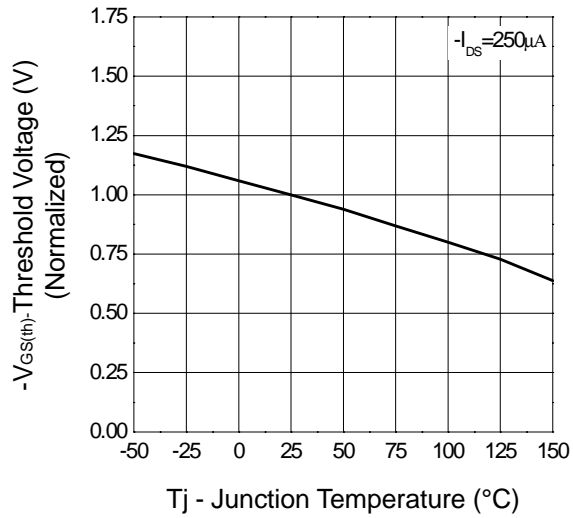
Output Characteristics



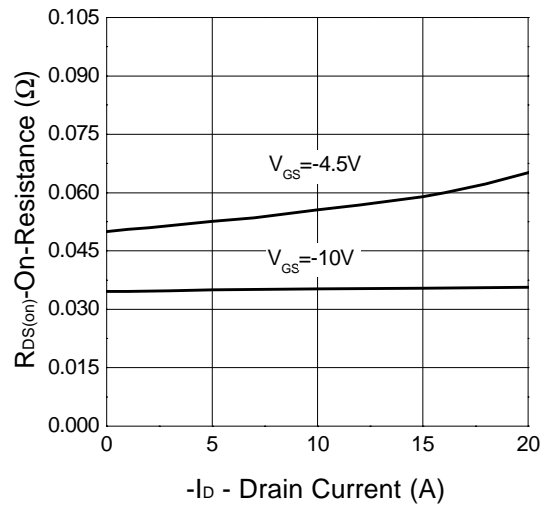
Transfer Characteristics



Threshold Voltage vs. Junction Temperature



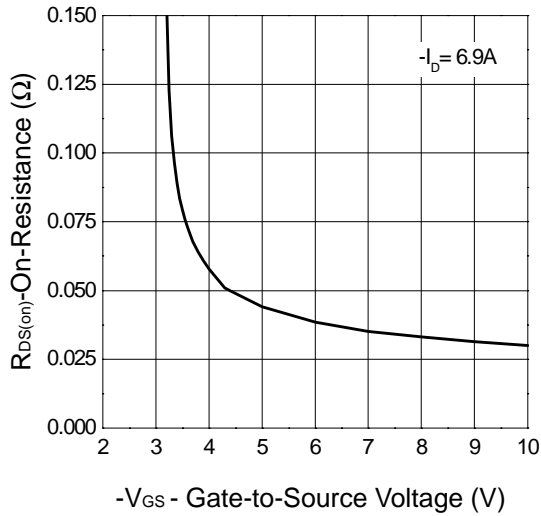
On-Resistance vs. Drain Current



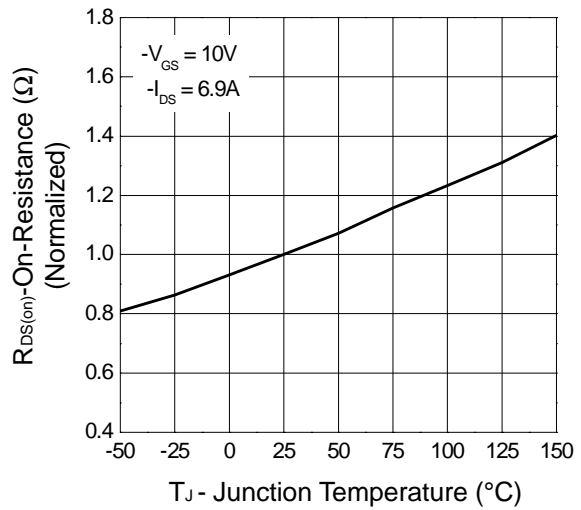
Typical Characteristics (Cont.)

P-Channel

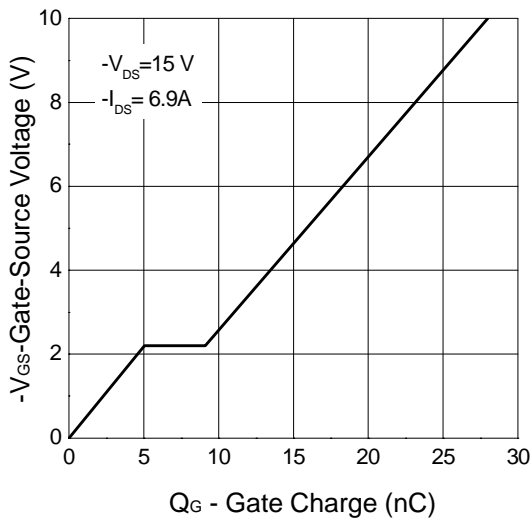
On-Resistance vs. Gate-to-Source Voltage



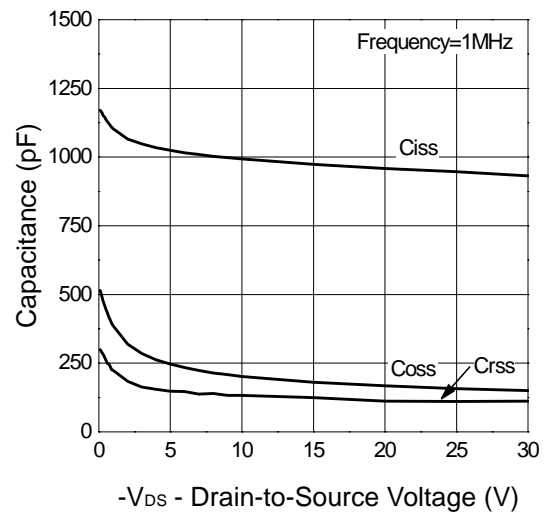
On-Resistance vs. Junction Temperature



Gate Charge



Capacitance



Typical Characteristics (Cont.)

P-Channel

